

# CMPA801B030S

## 7.9 - 11.0 GHz, 40 W, Packaged GaN MMIC Power Amplifier

#### **Description**

The CMPA801B030S is a packaged, 40W HPA utilizing the high performance, 0.15µm GaNon-Silicon Carbide production process. The CMPA801B030S operates from 7.9 - 11.0 GHz and targets pulsed radar systems supporting both defense and commercial applications. With 2 stages of gain, this high performance amplifier provides 20dB of large signal gain and 40% efficiency to support lower system DC power requirements and simplify system thermal management solutions. Packaged in a 7x7 mm plastic overmold QFN, the CMPA801B030S also supports reduced board space requirements and high-throughput manufacturing lines.



Package Type: 7x7 QFN PN:CMPA801B030S

#### Typical Performance Over 7.9 - 11.0 GHz ( $T_c = 25^{\circ}$ C)

Parameter	8.0 GHz	8.5 GHz	9.0 GHz	10.0 GHz	11.0 GHz	Units
Small Signal Gain	28.2	27.5	27.1	24.6	24.0	dB
Output Power	39.3	45.9	48.9	42.3	40.7	W
Power Gain	19.9	20.6	21.0	20.3	20.1	dB
Power Added Efficiency	38.2	40.6	41.3	39.4	37.0	%

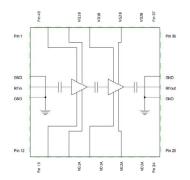
Note:  $P_{IN} = 26 \text{ dBm}$ , Pulse Width = 100 $\mu$ s; Duty Cycle = 10%

#### **Features**

- Freq: 7.9 11.0 GHz
- P<sub>SAT</sub>: 40 W
- PAE: 40%
- LS Gain: 20 dB
- 7x7 mm Overmold QFN
- Lower system costs
- Reduced board area

#### **Applications**

- Military pulsed radar
- Civil pulsed radar
- **Satellite Communications**



Features are typical performance across frequency under 25°C operation. Please reference performance charts for additional details.





### Absolute Maximum Ratings (not simultaneous) at 25°C

Parameter	Symbol	Rating	Units	Conditions
Drain-source Voltage	$V_{\scriptscriptstyle DSS}$	84	V	25°C
Gate-source Voltage	$V_{GS}$	-10, +2	$V_{DC}$	25 C
Storage Temperature	$T_{STG}$	-65, +150	°C	
Maximum Forward Gate Current	I <sub>G</sub>	12	mA	25°C
Maximum Drain Current	I <sub>DMAX</sub>	6	Α	
Soldering Temperature	Ts	260	°C	

### Electrical Characteristics (Frequency = 7.9 GHz to 11.0 GHz unless otherwise stated; $T_c = 25^{\circ}$ C)

Characteristics	Symbol	Min.	Тур.	Max.	Units	Conditions	
DC Characteristics							
Gate Threshold Voltage	$V_{GS(th)}$	-2.6	_	-1.6	V	$V_{DS} = 10 \text{ V}, I_{D} = 13 \text{ mA}$	
Gate Quiescent Voltage	$V_{GS(Q)}$	_	-1.75	_	$V_{DC}$	V <sub>DD</sub> = 28 V, I <sub>DQ</sub> = 800 mA	
Saturated Drain Current <sup>1</sup>	I <sub>DS</sub>	_	4	_	Α	V <sub>DS</sub> = 6.0 V, V <sub>GS</sub> = 2.0 V	
Drain-Source Breakdown Voltage	V <sub>BD</sub>	84	_	_	V	V <sub>GS</sub> = -8 V, I <sub>D</sub> = 13 mA	
RF Characteristics <sup>2,3</sup>							
Small Signal Gain at 8.0 GHz	S21 <sub>1</sub>	_	28.2	_			
Small Signal Gain at 8.5 GHz	S21 <sub>2</sub>	_	27.5	_			
Small Signal Gain at 9.0 GHz	S21 <sub>3</sub>	_	27.1	_	dB	$V_{DD} = 28 \text{ V}, I_{DQ} = 800 \text{ mA}$	
Small Signal Gain at 10.0 GHz	S21 <sub>4</sub>	_	24.6	_			
Small Signal Gain at 11.0 GHz	S21 <sub>5</sub>	_	24.0	_			
Output Power at 8.0 GHz	P <sub>OUT1</sub>	_	39.3	_			
Output Power at 8.5 GHz	P <sub>OUT2</sub>	_	45.9	_		V 20VI 000 A B 20 ID	
Output Power at 9.0 GHz	Роитз	_	48.9	_	w		
Output Power at 10.0 GHz	P <sub>OUT4</sub>	_	42.3	_			
Output Power at 11.0 GHz	P <sub>out5</sub>	_	40.7	_			
Power Added Efficiency at 8.0 GHz	PAE <sub>1</sub>	_	38	_		$V_{DD} = 28 \text{ V}, I_{DQ} = 800 \text{ mA}, P_{IN} = 26 \text{ dBm}$	
Power Added Efficiency at 8.5 GHz	PAE <sub>2</sub>	_	41	_			
Power Added Efficiency at 9.0 GHz	PAE <sub>3</sub>	_	41	_	%		
Power Added Efficiency at 10.0 GHz	PAE <sub>4</sub>	_	39	_			
Power Added Efficiency at 11.0 GHz	PAE₅	_	37	_			
Power Gain	G <sub>P</sub>		21.0	_			
Input Return Loss	S11	_	-13	_	dB	$V_{DD} = 28 \text{ V}, I_{DQ} = 800 \text{ mA}$	
Output Return Loss	S12	_	-10	_			
Output Mismatch Stress	VSWR		_	5:1	Ψ	No damage at all phase angles, $V_{DD} = 28 \text{ V}$ , $I_{DQ} = 800 \text{ mA}$	

#### Notes:

<sup>&</sup>lt;sup>1</sup>Scaled from PCM data

<sup>&</sup>lt;sup>2</sup> All data pulse tested in CMPA801B030S-AMP1

<sup>&</sup>lt;sup>3</sup> Pulse Width = 100μs; Duty Cycle = 10%



#### **Thermal Characteristics**

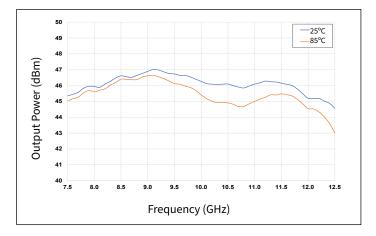
Parameter	Symbol	Rating	Units	Conditions
Operating Junction Temperature	TJ	225	°C	
Thermal Resistance, Junction to Case (packaged) <sup>1</sup>	$R_{\theta JC}$	2.5	°C/W	100μs, 10%, P <sub>DISS</sub> = 25.5 W

#### Notes

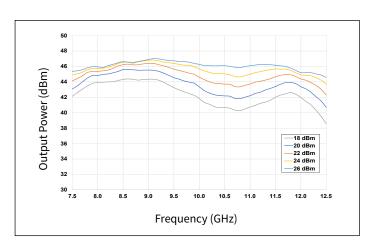
 $<sup>^{1}</sup>$  Measured for the CMPA801B030S at P<sub>DISS</sub> = 25.5 W



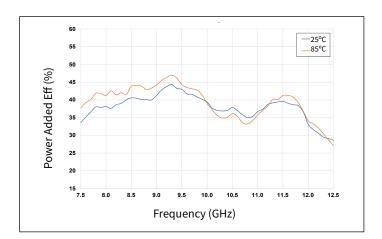
Test conditions unless otherwise noted:  $V_D = 28 \text{ V}$ ,  $I_{DO} = 800 \text{ mA}$ ,  $PW = 100 \mu s$ , DC = 10%,  $P_{IN} = 26 \text{ dBm}$ ,  $T_{BASE} = +25 ^{\circ} \text{C}$ 



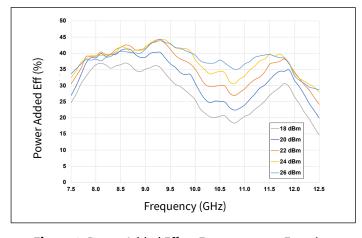
**Figure 1.** Output Power vs Frequency as a Function of Temperature



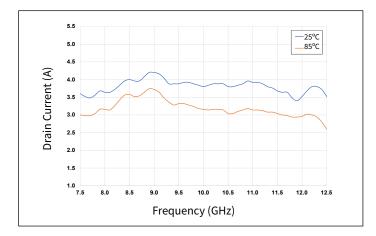
**Figure 2.** Output Power vs Frequency as a Function of Input Power



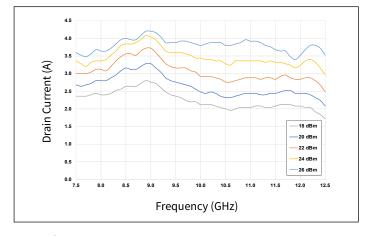
**Figure 3.** Power Added Eff. vs Frequency as a Function of Temperature



**Figure 4.** Power Added Eff. vs Frequency as a Function of Input Power



**Figure 5.** Drain Current vs Frequency as a Function of Temperature



**Figure 6.** Drain Current vs Frequency as a Function of Input Power

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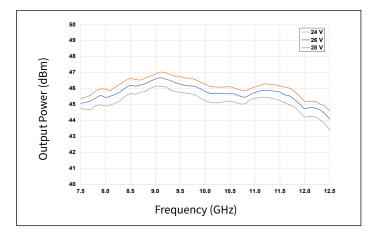


Figure 7. Output Power vs Frequency as a Function of V<sub>D</sub>

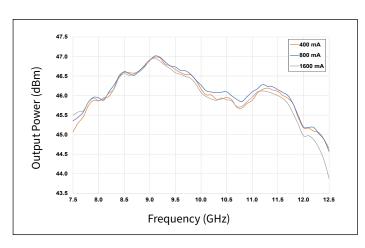


Figure 8. Output Power vs Frequency as a Function of IDQ

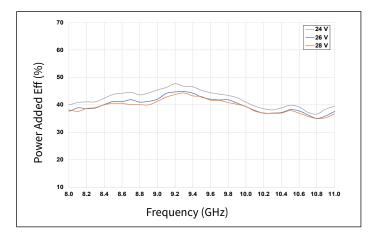
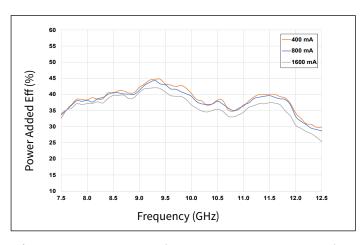


Figure 9. Power Added Eff. vs Frequency as a Function of V<sub>D</sub>



**Figure 10.** Power Added Eff. vs Frequency as a Function of I<sub>DO</sub>

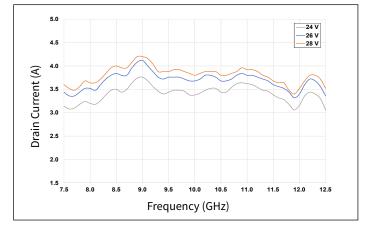


Figure 11. Drain Current vs Frequency as a Function of V<sub>D</sub>

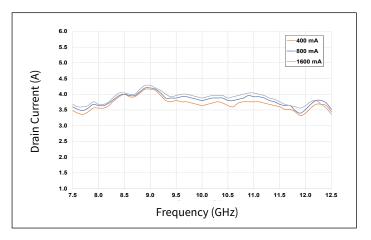
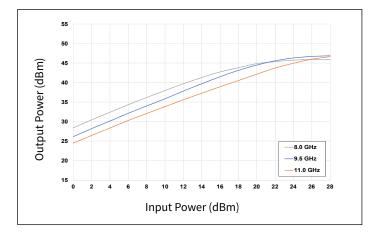
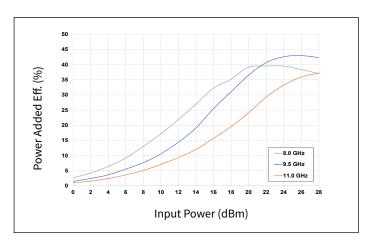


Figure 12. Drain Current vs Frequency as a Function of I<sub>DO</sub>

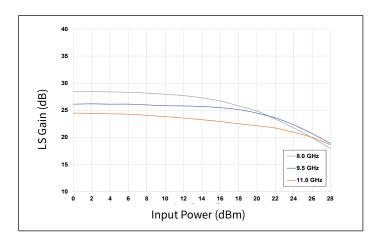




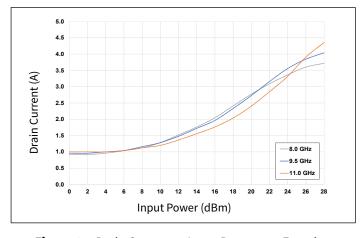
**Figure 13.** Output Power vs Input Power as a Function of Frequency



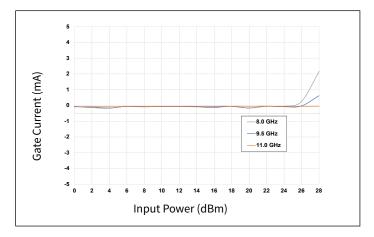
**Figure 14.** Power Added Eff. vs Input Power as a Function of Frequency



**Figure 15.** Large Signal Gain vs Input Power as a Function of Frequency

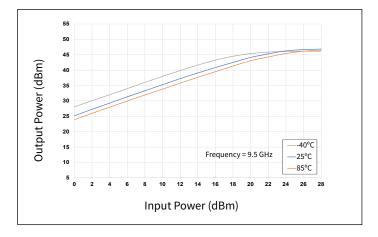


**Figure 16.** Drain Current vs Input Power as a Function of Frequency



**Figure 17.** Gate Current vs Input Power as a Function of Frequency

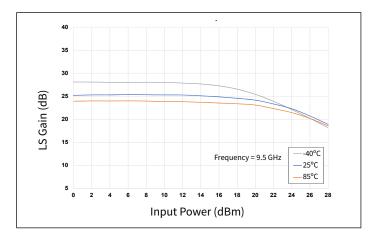




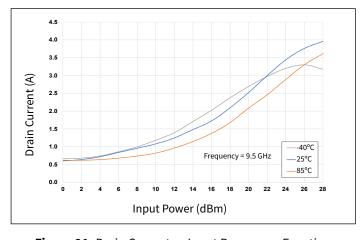
**Figure 18.** Output Power vs Input Power as a Function of Temperature



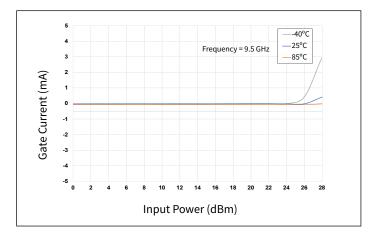
**Figure 19.** Power Added Eff. vs Input Power as a Function of Temperature



**Figure 20.** Large Signal Gain vs Input Power as a Function of Temperature



**Figure 21.** Drain Current vs Input Power as a Function of Temperature



**Figure 22.** Gate Current vs Input Power as a Function of Temperature



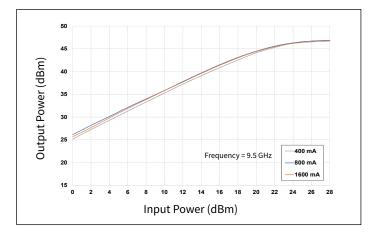
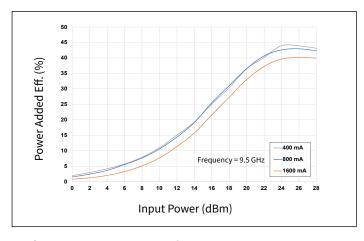
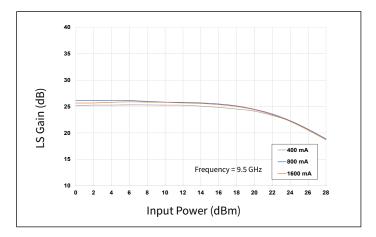


Figure 23. Output Power vs Input Power as a Function of  $I_{DQ}$ 



**Figure 24.** Power Added Eff. vs Input Power as a Function of  $I_{DO}$ 



**Figure 25.** Large Signal Gain vs Input Power as a Function of  $I_{DO}$ 

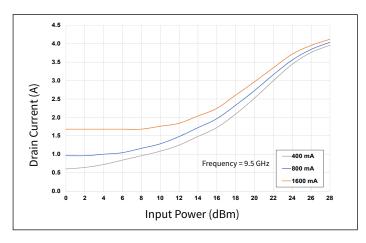
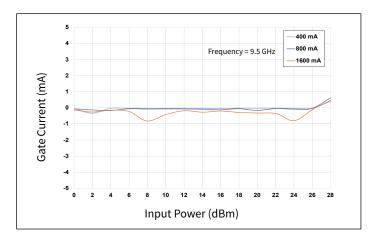
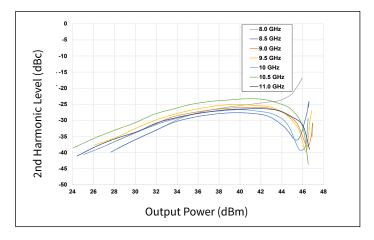


Figure 26. Drain Current vs Input Power as a Function of I<sub>DO</sub>

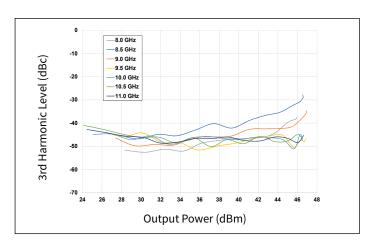


**Figure 27.** Gate Current vs Input Power as a Function of  $I_{DQ}$ 

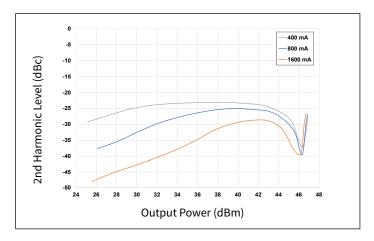




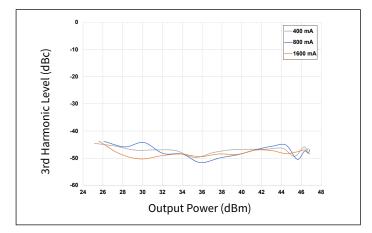
**Figure 28.** 2nd Harmonic vs Output Power as a Function of Frequency



**Figure 29.** 3rd Harmonic vs Output Power as a Function of Frequency

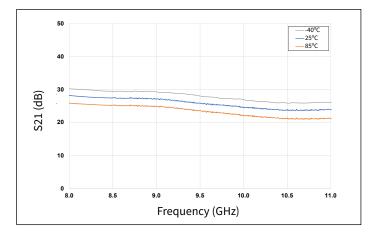


**Figure 30.** 2nd Harmonic vs Output Power as a Function of  $I_{DO}$ 



**Figure 31.** 3rd Harmonic vs Output Power as a Function of  $I_{DQ}$ 

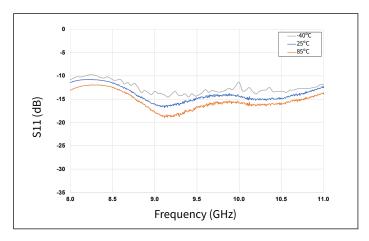




−25°C −85°C S21 (dB) 10 ..... Frequency (GHz)

Figure 32. Gain vs Frequency as a Function of Temperature

Figure 33. Gain vs Frequency as a Function of Temperature



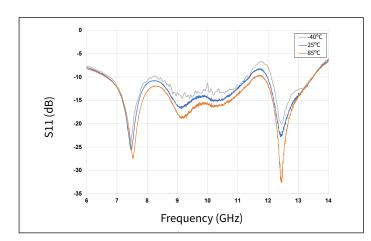
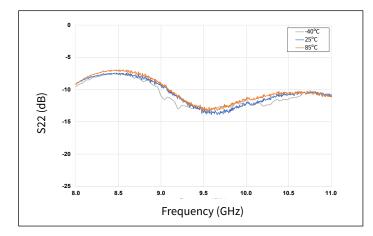


Figure 34. Input RL vs Frequency as a Function of Temperature

Figure 35. Input RL vs Frequency as a Function of Temperature



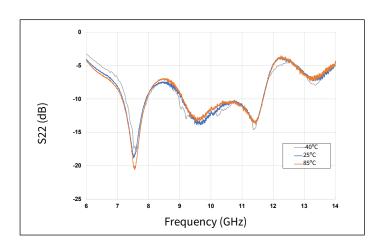


Figure 36. Output RL vs Frequency as a Function of Temperature

Figure 37. Output RL vs Frequency as a Function of Temperature



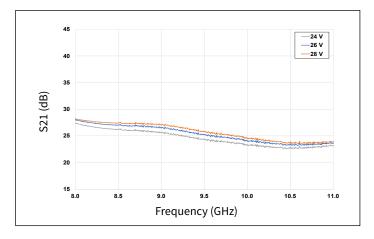


Figure 38. Gain vs Frequency as a Function of Voltage

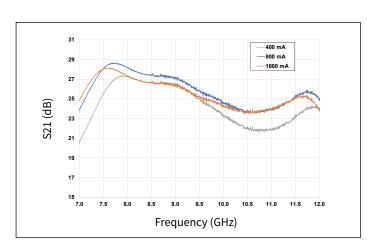


Figure 39. Gain vs Frequency as a Function of IDQ

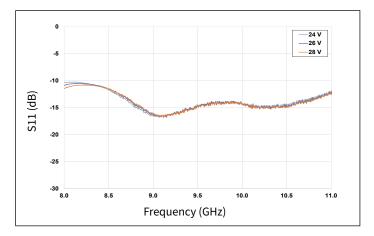
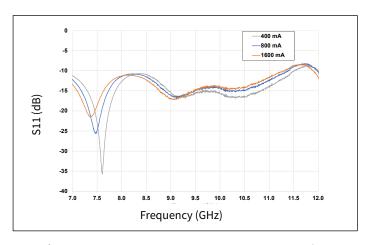


Figure 40. Input RL vs Frequency as a Function Voltage



**Figure 41.** Input RL vs Frequency as a Function of I<sub>DO</sub>

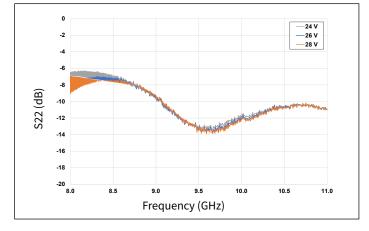


Figure 42. Output RL vs Frequency as a Function of Voltage

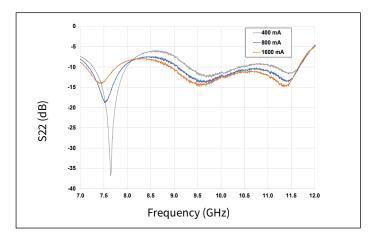
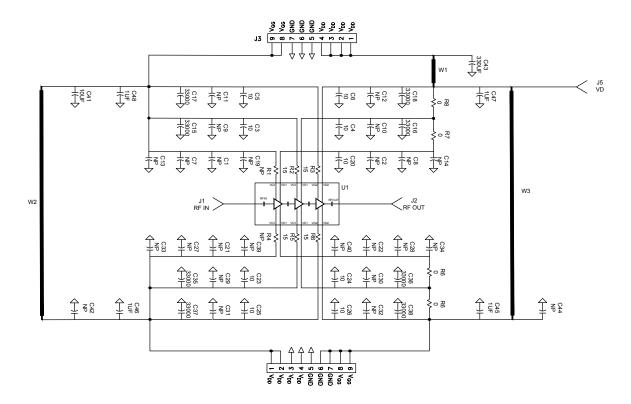


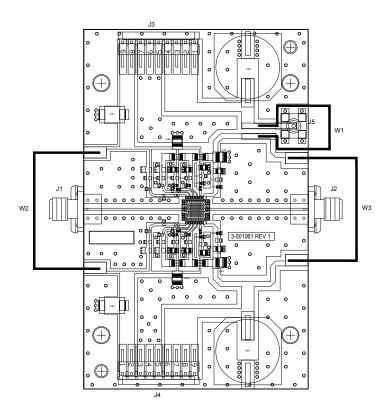
Figure 43. Output RL vs Frequency as a Function of IDO



### CMPA801B030S-AMP1 Application Circuit



### CMPA801B030S-AMP1 Evaluation Board Layout





#### CMPA801B030S-AMP1 Evaluation Board Bill of Materials

Designator	Description	Qty
C3, C4, C5, C6, C23, C24, C25, C26	CAP, 10pF, +/-5%, pF, 200V, 0402	8
C15, C16, C17, C18, C35, C36, C37, C38	CA, 330000pF, 0805,100V, X7R	8
C45, C46, C47, C48	CAP, 1.0μF, 100V, 10%, X7R, 1210	4
C41	CAP 10μF 16V TANTALUM, 2312	1
C43	CAP, 330μF, +/-20%, 100V, ELECTROLYTIC, CASE SIZE K16	1
R2, R3, R5, R6	RES 15 OHM, +/-1%, 1/16W, 0402	6
R8, R10	RES 0.0 OHM 1/16W 1206 SMD	2
J1,J2	CONN, SMA, PANEL MOUNT JACK, FLANGE, 4-HOLE, BLUNT POST, 20MIL	4
J5	CONN, SMB, STRAIGHT JACK RECEPTACLE, SMT, 50 OHM, Au PLATED	1
J3, J4	HEADER RT>PLZ .1CEN LK 9POS	1
W2, W3	WIRE, BLACK, 20 AWG ~ 2.5"	2
W1	WIRE, BLACK, 20 AWG ~ 3.0"	1
	PCB, TEST FIXTURE, RF-35TC, 0.010 THK, 7X7 Overmold QFN SOCKET BOARD	1
	2-56 SOC HD SCREW 3/16 SS	4
	#2 SPLIT LOCKWASHER SS	4
Q1	CMPA801B030S	1

### **Electrostatic Discharge (ESD) Classifications**

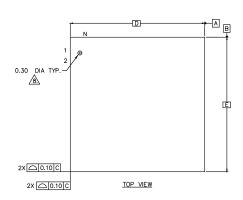
Parameter	Symbol	Class	Classification Level	Test Methodology
Human Body Model	НВМ	1A	ANSI/ESDA/JEDEC JS-001 Table 3	JEDEC JESD22 A114-D
Charge Device Model	CDM	C2B	ANSI/ESDA/JEDEC JS-002 Table 3	JEDEC JESD22 C101-C

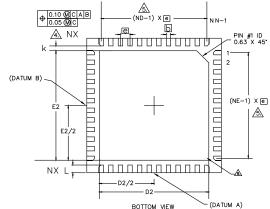
### **Moisture Sensitivity Level (MSL) Classification**

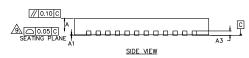
Parameter	Symbol	Level	Test Methodology
Moisture Sensitivity Level	MSL	3 (168 hours)	IPC/JEDEC J-STD-20



### Product Dimensions CMPA801B030S (Package Type - 7x7 QFN)







#### NOTES

- UIES :

  1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M. 1994.

  2. ALL DIMENSION'S ARE IN MILLIMETERS, 0 IS IN DEGREES.

  3. N IS THE TOTAL NUMBER OF TERMINALS.

  \$\frac{1}{2}\] NICHARM OF TOTAL NUMBER OF TERMINALS AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM TERMINAL ITP.

  5. NO AND NE REFER TO THE NUMBER OF TERMINALS ON EACH D AND E SIDE RESPECTIVELY.

  6. MAX. PACKAGE WARPAGE IS 0.05 mm.

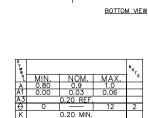
  7. MAXIMUM ALLOWABLE BURRS IS 0.076 mm IN ALL DIRECTIONS.

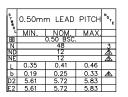
  8. PIN ALL ID NO YED WILL BE I ASFER MARKED.

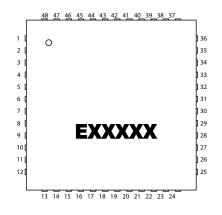
- A PIN #1 ID ON TOP WILL BE LASER MARKED.
- 9. BILATERAL COPLANARITY ZONE APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE
- TERMINALS.

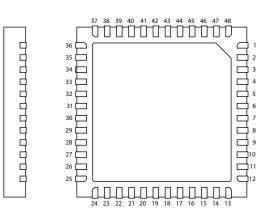
  10. THIS DRAWING CONFORMS TO JEDEC REGISTERED OUTLINE MO-220

  11. ALL PLATED SURFACES ARE TIN 0.010 mm +/- 0.005mm.









PIN	DESC.	PIN	DESC.	PIN	DESC.	PIN	DESC.
1	NC	15	NC	29	NC	43	NC
2	NC	16	NC	30	RFGND	44	VG1B
3	NC	17	VG1A	31	RFOUT	45	NC
4	NC	18	NC	32	RFGND	46	NC
5	RFGND	19	VD1A	33	NC	47	NC
6	RFIN	20	NC	34	NC	48	NC
7	RFGND	21	VG2A	35	NC		
8	NC	22	NC	36	NC		
9	NC	23	VD2A	37	NC		
10	NC	24	NC	38	VD2B		
11	NC	25	NC	39	NC		
12	NC	26	NC	40	VG2B		
13	NC	27	NC	41	NC		
14	NC	28	NC	42	VD1B		



#### **Part Number System**

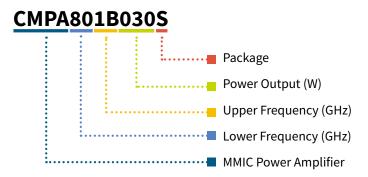


Table 1.

Parameter	Parameter Value	
Lower Frequency	7.9	CII-
Upper Frequency	11.0	GHz
Power Output	40	W
Package	Surface Mount	_

#### Note:

Table 2.

Character Code	Code Value
A	0
В	1
С	2
D	3
E	4
F	5
G	6
Н	7
J	8
К	9
Examples	1A = 10.0 GHz 2H = 27.0 GHz

<sup>&</sup>lt;sup>1</sup> Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value.



## **Product Ordering Information**

Order Number	Description	Unit of Measure	Image
CMPA801B030S	Packaged GaN MMIC PA	Each	The state of the s
CMPA801B030S-AMP1	Evaluation Board with GaN MMIC Installed	Each	



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